Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**

**ANODE**

**.007 x .007”**

**.015”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size = .007 X .007”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .015” X .015” DATE: 11/1/21**

**MFG: MICROSEMI THICKNESS .007” P/N: 1N4152**

**DG 10.1.2**

#### Rev B, 7/1